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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	2400
Number of Logic Elements/Cells	10800
Total RAM Bits	573440
Number of I/O	404
Number of Gates	129600
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	560-LBGA Exposed Pad, Metal
Supplier Device Package	560-MBGA (42.5x42.5)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xcv405e-7bg560i

Architectural Description

Virtex-E Array

The Virtex-E user-programmable gate array (see Figure 1) comprises two major configurable elements: configurable logic blocks (CLBs) and input/output blocks (IOBs).

- CLBs provide the functional elements for constructing logic.
- IOBs provide the interface between the package pins and the CLBs.

CLBs interconnect through a general routing matrix (GRM). The GRM comprises an array of routing switches located at the intersections of horizontal and vertical routing channels. Each CLB nests into a VersaBlock™ that also provides local routing resources to connect the CLB to the GRM.

The VersaRing™ I/O interface provides additional routing resources around the periphery of the device. This routing improves I/O routability and facilitates pin locking.

The Virtex-E architecture also includes the following circuits that connect to the GRM:

- Dedicated block memories of 4096 bits each
- Clock DLLs for clock-distribution delay compensation and clock domain control
- 3-State buffers (BUFTs) associated with each CLB that drive dedicated segmentable horizontal routing resources

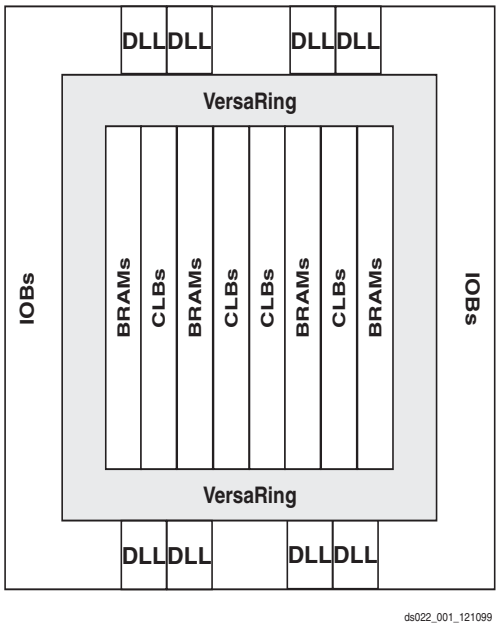

Figure 1: **Virtex-E Architecture Overview**

Values stored in static memory cells control the configurable logic elements and interconnect resources. These values load into the memory cells on power-up, and can reload if necessary to change the function of the device.

Input/Output Block

The Virtex-E IOB, Figure 2, features SelectIO+™ inputs and outputs that support a wide variety of I/O signalling standards (see Table 1).

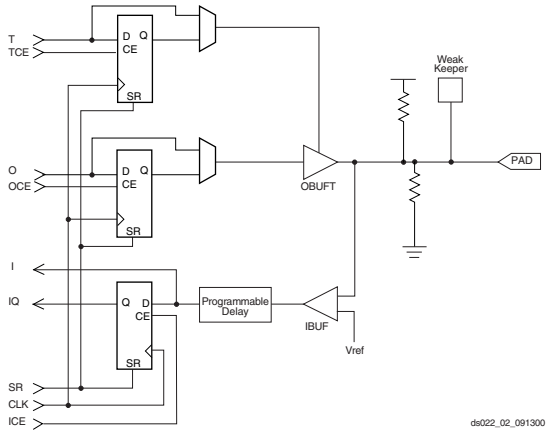

Figure 2: **Virtex-E Input/Output Block (IOB)**

The three IOB storage elements function either as edge-triggered D-type flip-flops or as level-sensitive latches. Each IOB has a clock signal (CLK) shared by the three flip-flops and independent clock enable signals for each flip-flop.

Figure 11 is a diagram of the Virtex-E Series boundary scan logic. It includes three bits of Data Register per IOB, the IEEE 1149.1 Test Access Port controller, and the Instruction Register with decodes.

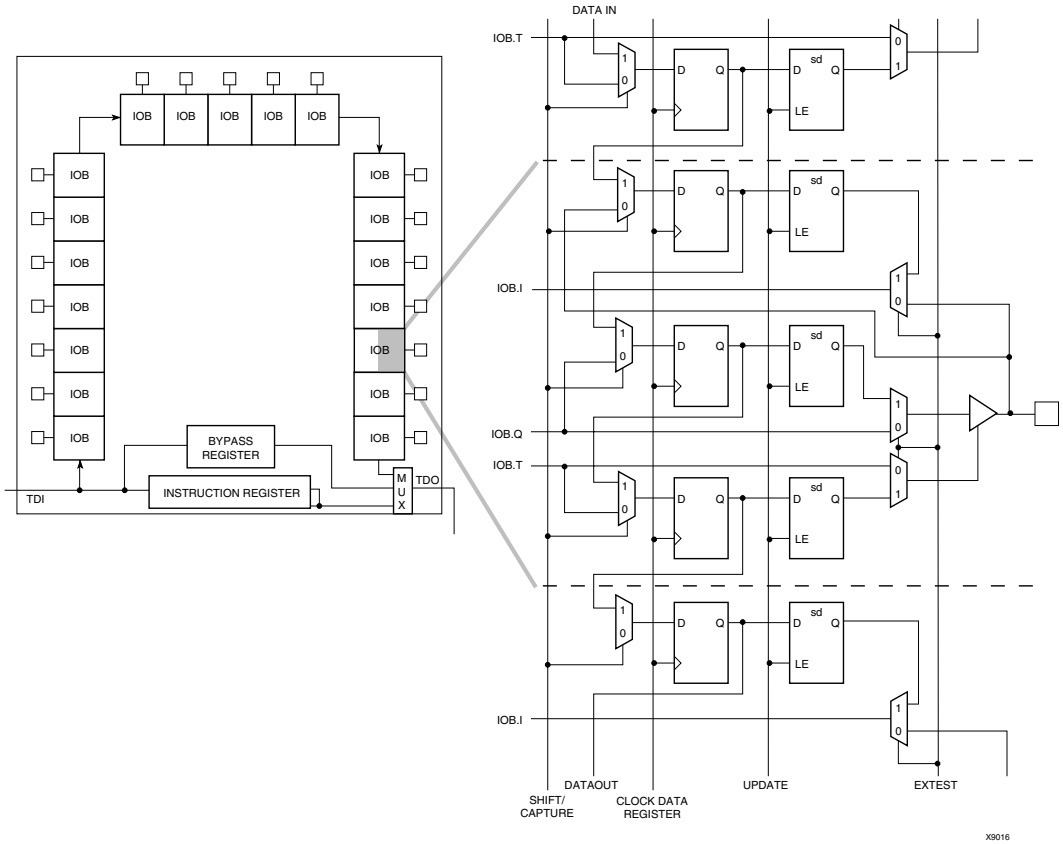

Figure 11: **Virtex-E Family Boundary Scan Logic**

Table 8: **Configuration Codes**

Configuration Mode	M2	M1	M0	CCLK Direction	Data Width	Serial D_{out}	Configuration Pull-ups
Boundary-scan mode	0	0	1	N/A	1	No	Yes
SelectMAP mode	0	1	0	In	8	No	Yes
Slave-serial mode	0	1	1	In	1	Yes	Yes

Table 9 lists the total number of bits required to configure each device.

Table 9: **Virtex-E Bitstream Lengths**

Device	# of Configuration Bits
XCV405E	3,430,400
XCV812E	6,519,648

Slave-Serial Mode

In slave-serial mode, the FPGA receives configuration data in bit-serial form from a serial PROM or other source of serial configuration data. The serial bitstream must be set up at the DIN input pin a short time before each rising edge of an externally generated CCLK.

For more detailed information on serial PROMs see the PROM data sheet at http://www.xilinx.com/bvdocs/publications/ds026.pdf.

Multiple FPGAs can be daisy-chained for configuration from a single source. After a particular FPGA has been configured, the data for the next device is routed to the DOUT pin. Data on the DOUT pin changes on the rising edge of CCLK.

The change of DOUT on the rising edge of CCLK differs from previous families but does not cause a problem for mixed configuration chains. This change was made to improve serial configuration rates for Virtex and Virtex-E only chains.

Figure 13 shows a full master/slave system. A Virtex-E device in slave-serial mode should be connected as shown in the right-most device.

Slave-serial mode is selected by applying <111> or <011> to the mode pins (M2, M1, M0). A weak pull-up on the mode pins makes slave-serial the default mode if the pins are left unconnected. However, it is recommended to drive the configuration mode pins externally. Figure 14 shows slave-serial mode programming switching characteristics.

Table 10 provides more detail about the characteristics shown in Figure 14. Configuration must be delayed until the $\overline{INIT}$ pins of all daisy-chained FPGAs are High.

Table 10: **Master/Slave Serial Mode Programming Switching**

	Description	Figure References	Symbol	Values	Units
CCLK	DIN setup/hold, slave mode	1/2	T_{DCC}/T_{CCD}	5.0/0.0	ns, min
	DIN setup/hold, master mode	1/2	T_{DSCK}/T_{CKDS}	5.0/0.0	ns, min
	DOUT	3	T_{CCO}	12.0	ns, max
	High time	4	T_{CCH}	5.0	ns, min
	Low time	5	T_{CCL}	5.0	ns, min
	Maximum Frequency		F_{CC}	66	MHz, max
	Frequency Tolerance, master mode with respect to nominal			+45% –30%	

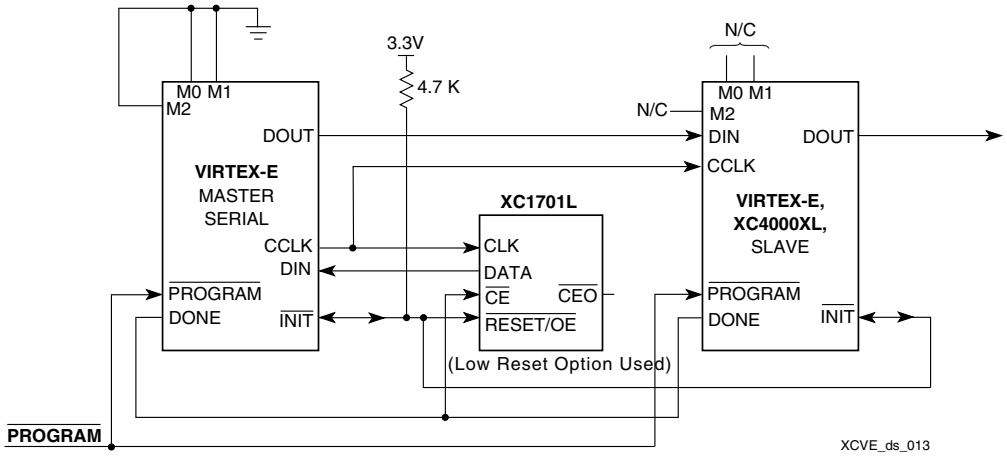

Figure 13: **Master/Slave Serial Mode Circuit Diagram**

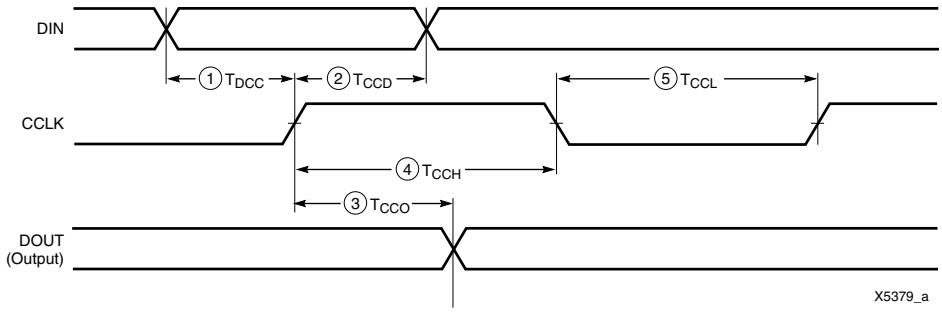

Figure 14: **Slave-Serial Mode Programming Switching Characteristics**

Master-Serial Mode

In master-serial mode, the CCLK output of the FPGA drives a Xilinx Serial PROM that feeds bit-serial data to the DIN input. The FPGA accepts this data on each rising CCLK edge. After the FPGA has been loaded, the data for the next device in a daisy-chain is presented on the DOUT pin after the rising CCLK edge.

The interface is identical to slave-serial except that an internal oscillator is used to generate the configuration clock (CCLK). A wide range of frequencies can be selected for CCLK which always starts at a slow default frequency. Configuration bits then switch CCLK to a higher frequency for the remainder of the configuration. Switching to a lower frequency is prohibited.

The CCLK frequency is set using the ConfigRate option in the bitstream generation software. The maximum CCLK frequency that can be selected is 60 MHz. When selecting a CCLK frequency, ensure that the serial PROM and any daisy-chained FPGAs are fast enough to support the clock rate.

On power-up, the CCLK frequency is approximately 2.5 MHz. This frequency is used until the ConfigRate bits have been loaded when the frequency changes to the selected ConfigRate. Unless a different frequency is specified in the design, the default ConfigRate is 4 MHz.

Figure 13 shows a full master/slave system. In this system, the left-most device operates in master-serial mode. The remaining devices operate in slave-serial mode. The SPROM $\overline{\text{RESET}}$ pin is driven by $\overline{\text{INIT}}$, and the $\overline{\text{CE}}$ input is driven by DONE. There is the potential for contention on the DONE pin, depending on the start-up sequence options chosen.

The sequence of operations necessary to configure a Virtex-E FPGA serially appears in Figure 15.

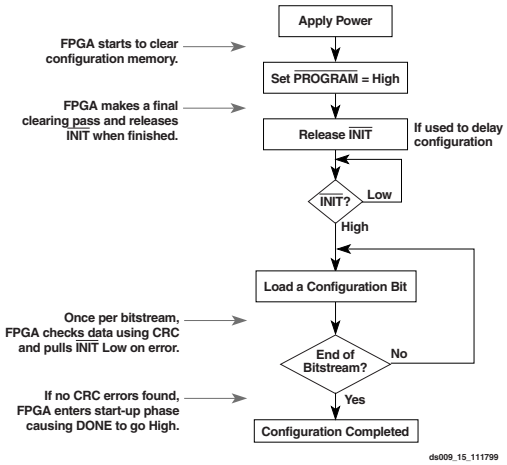

Figure 15: **Serial Configuration Flowchart**

Figure 16 shows the timing of master-serial configuration. Master-serial mode is selected by a <000> or <100> on the mode pins (M2, M1, M0). Table 10 shows the timing information for Figure 16

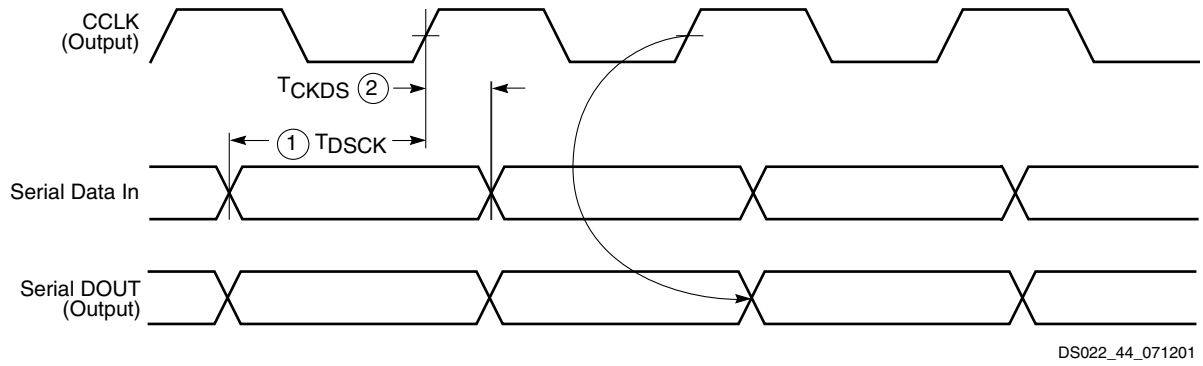

Figure 16: **Master-Serial Mode Programming Switching Characteristics**

At power-up, V_{CC} must rise from 1.0 V to V_{CC} min in less than 50 ms, otherwise delay configuration by pulling $\overline{\text{PROGRAM}}$ Low until V_{CC} is valid.

SelectMAP Mode

The SelectMAP mode is the fastest configuration option. Byte-wide data is written into the FPGA with a BUSY flag controlling the flow of data.

An external data source provides a byte stream, CCLK, a Chip Select ($\overline{\text{CS}}$) signal and a Write signal ($\overline{\text{WRITE}}$). If BUSY is asserted (High) by the FPGA, the data must be held until BUSY goes Low.

Data can also be read using the SelectMAP mode. If $\overline{\text{WRITE}}$ is not asserted, configuration data is read out of the FPGA as part of a readback operation.

After configuration, the pins of the SelectMAP port can be used as additional user I/O. Alternatively, the port can be retained to permit high-speed 8-bit readback.

Retention of the SelectMAP port is selectable on a design-by-design basis when the bitstream is generated. If retention is selected, PROHIBIT constraints are required to prevent SelectMAP-port pins from being used as user I/O.

Multiple Virtex-E FPGAs can be configured using the SelectMAP mode, and be made to start-up simultaneously. To configure multiple devices in this way, wire the individual CCLK, Data, $\overline{\text{WRITE}}$, and BUSY pins of all the devices in parallel. The individual devices are loaded separately by asserting the $\overline{\text{CS}}$ pin of each device in turn and writing the appropriate data. See Table 11 for SelectMAP Write Timing Characteristics.

Write

Write operations send packets of configuration data into the FPGA. The sequence of operations for a multi-cycle write operation is shown below. Note that a configuration packet can be split into many such sequences. The packet does not have to complete within one assertion of $\overline{\text{CS}}$, illustrated in Figure 17.

1. Assert $\overline{\text{WRITE}}$ and $\overline{\text{CS}}$ Low. Note that when $\overline{\text{CS}}$ is asserted on successive CCLKs, $\overline{\text{WRITE}}$ must remain

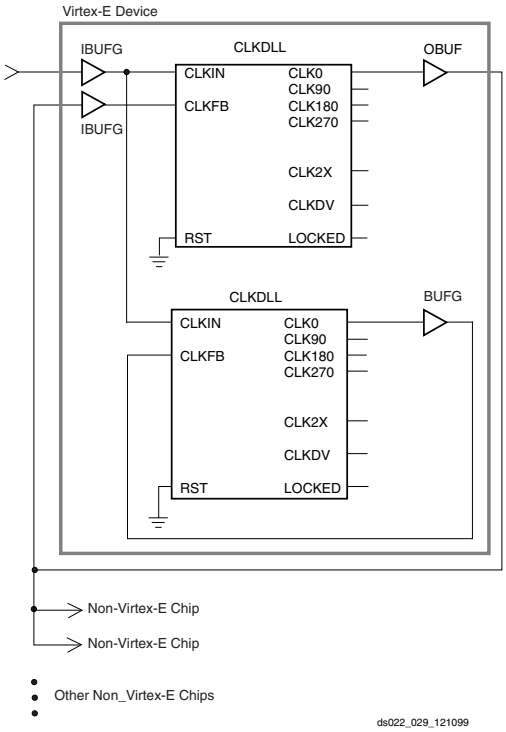

Figure 28: **DLL De-skew of Board Level Clock**

Board-level de-skew is not required for low-fanout clock networks. It is recommended for systems that have fanout limitations on the clock network, or if the clock distribution chip cannot handle the load.

Do not use the DLL output clock signals until after activation of the LOCKED signal. Prior to the activation of the LOCKED signal, the DLL output clocks are not valid and can exhibit glitches, spikes, or other spurious movement.

The dll_mirror_1 files in the xapp132.zip file show the VHDL and Verilog implementation of this circuit.

De-Skew of Clock and Its 2x Multiple

The circuit shown in Figure 29 implements a 2x clock multiplier and also uses the CLK0 clock output with zero ns skew between registers on the same chip. A clock divider circuit could alternatively be implemented using similar connections.

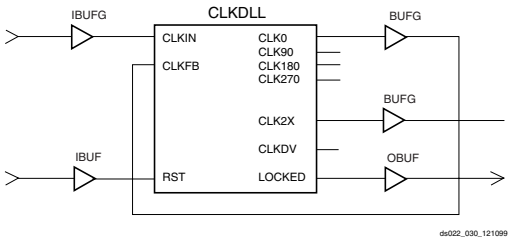

Figure 29: **DLL De-skew of Clock and 2x Multiple**

Because any single DLL can access only two BUFGs at most, any additional output clock signals must be routed from the DLL in this example on the high speed backbone routing.

The dll_2x files in the xapp132.zip file show the VHDL and Verilog implementation of this circuit.

Virtex-E 4x Clock

Two DLLs located in the same half-edge (top-left, top-right, bottom-right, bottom-left) can be connected together, without using a BUFG between the CLKDLLs, to generate a 4x clock as shown in Figure 30. Virtex-E devices, like the Virtex devices, have four clock networks that are available for internal de-skewing of the clock. Each of the eight DLLs have access to two of the four clock networks. Although all the DLLs can be used for internal de-skewing, the presence of two GCLKBUFs on the top and two on the bottom indicate that only two of the four DLLs on the top (and two of the four DLLs on the bottom) can be used for this purpose.

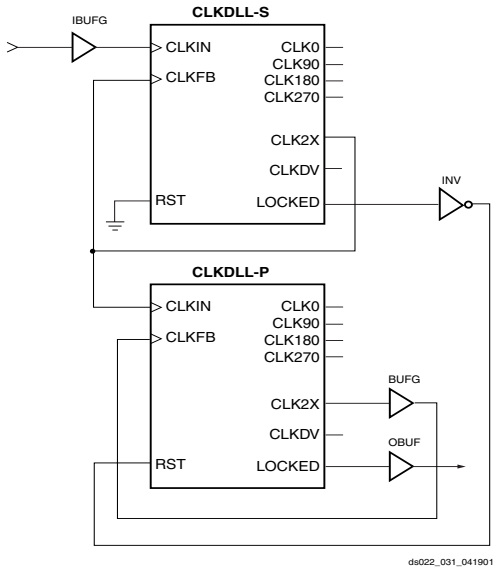

Figure 30: **DLL Generation of 4x Clock in Virtex-E Devices**

The dll_4xe files in the xapp 32.zip file show the DLL implementation in Verilog for Virtex-E devices. These files can be found at:

ftp://ftp.xilinx.com/pub/applications/xapp/xapp132.zip

Using Block SelectRAM+ Features

The Virtex FPGA Series provides dedicated blocks of on-chip, true dual-read/write port synchronous RAM, with 4096 memory cells. Each port of the block SelectRAM+ memory can be independently configured as a read/write port, a read port, a write port, and can be configured to a specific data width. block SelectRAM+ memory offers new capabilities, allowing FPGA designers to simplify designs.

HSTL

A sample circuit illustrating a valid termination technique for HSTL_I appears in Figure 46. A sample circuit illustrating a valid termination technique for HSTL_III appears in Figure 47.

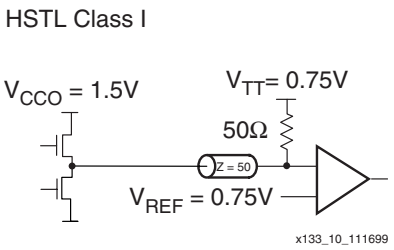

Figure 46: **Terminated HSTL Class I**

Table 25: **HSTL Class I Voltage Specification**

Parameter	Min	Typ	Max
V_{CCO}	1.40	1.50	1.60
V_{REF}	0.68	0.75	0.90
V_{TT}	-	$V_{CCO} \times 0.5$	-
V_{IH}	V_{REF} + 0.1	-	-
V_{IL}	-	-	V_{REF} – 0.1
V_{OH}	V_{CCO} – 0.4	-	-
V_{OL}			0.4
I_{OH} at V_{OH} (mA)	–8	-	-
I_{OL}at V_{OL} (mA)	8	-	-

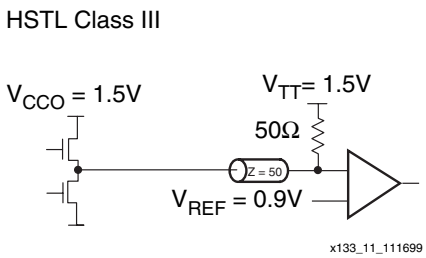

Figure 47: **Terminated HSTL Class III**

Table 26: **HSTL Class III Voltage Specification**

Parameter	Min	Typ	Max
V_{CCO}	1.40	1.50	1.60
V_{REF} (1)	-	0.90	-
V_{TT}	-	V_{CCO}	-
V_{IH}	V_{REF} + 0.1	-	-
V_{IL}	-	-	V_{REF} – 0.1
V_{OH}	V_{CCO} – 0.4	-	-
V_{OL}	-	-	0.4
I_{OH} at V_{OH} (mA)	–8	-	-
I_{OL}at V_{OL} (mA)	24	-	-

Note: Per EIA/JESD8-6, "The value of V_{REF} is to be selected by the user to provide optimum noise margin in the use conditions specified by the user."

A sample circuit illustrating a valid termination technique for HSTL_IV appears in Figure 48.

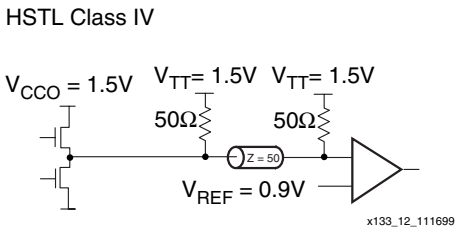

Figure 48: **Terminated HSTL Class IV**

Table 27: **HSTL Class IV Voltage Specification**

Parameter	Min	Typ	Max
V_{CCO}	1.40	1.50	1.60
V_{REF}	-	0.90	-
V_{TT}	-	V_{CCO}	-
V_{IH}	V_{REF} + 0.1	-	-
V_{IL}	-	-	V_{REF} – 0.1
V_{OH}	V_{CCO} – 0.4	-	-
V_{OL}	-	-	0.4
I_{OH} at V_{OH} (mA)	–8	-	-
I_{OL}at V_{OL} (mA)	48	-	-

Note: Per EIA/JESD8-6, "The value of V_{REF} is to be selected by the user to provide optimum noise margin in the use conditions specified by the user.

Termination Resistor Packs

Resistor packs are available with the values and the configuration required for LVDS and LVPECL termination from Bourns, Inc., as listed in Table. For pricing and availability, please contact Bourns directly at www.bourns.com.

Table 40: **Bourns LVDS/LVPECL Resistor Packs**

Part Number	I/O Standard	Term. for:	Pairs/ Pack	Pins
CAT16–LV2F6	LVDS	Driver	2	8
CAT16–LV4F12	LVDS	Driver	4	16
CAT16–PC2F6	LVPECL	Driver	2	8
CAT16–PC4F12	LVPECL	Driver	4	16
CAT16–PT2F2	LVDS/LVPECL	Receiver	2	8
CAT16–PT4F4	LVDS/LVPECL	Receiver	4	16

LVDS Design Guide

The SelectI/O library elements have been expanded for Virtex-E devices to include new LVDS variants. At this time all of the cells might not be included in the Synthesis libraries. The 2.1i-Service Pack 2 update for Alliance and Foundation software includes these cells in the VHDL and Verilog libraries. It is necessary to combine these cells to create the P-side (positive) and N-side (negative) as described in the input, output, 3-state and bidirectional sections.

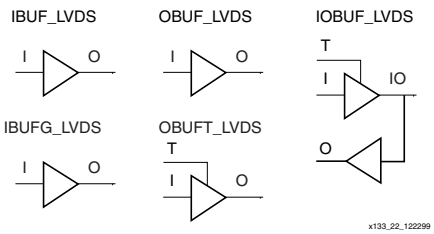

Figure 58: **LVDS Elements**

Creating LVDS Global Clock Input Buffers

The global clock input buffer can be combined with the adjacent IOB to form an LVDS clock input buffer. The P-side resides in the GCLKPAD location and the N-side resides in the adjacent IO_LVDS_DLL site.

Table 41: **Global Clock Input Buffer Pair Locations**

Pkg	Pair 3		Pair 2		Pair 2		Pair 0	
	P	N	P	N	P	N	P	N
BG560	A17	C18	D17	E17	AJ17	AM18	AL17	AM17
FG676	E13	B13	C13	F14	AB13	AF13	AA14	AC14
FG900	C15	A15	E15	E16	AK16	AH16	AJ16	AF16

HDL Instantiation

Only one global clock input buffer is required to be instantiated in the design and placed on the correct GCLKPAD location. The N-side of the buffer is reserved and no other IOB is allowed to be placed on this location.

In the physical device, a configuration option is enabled that routes the pad wire to the differential input buffer located in the GCLKIOB. The output of this buffer then drives the output of the GCLKIOB cell. In EPIC it appears that the second buffer is unused. Any attempt to use this location for another purpose leads to a DRC error in the software.

VHDL Instantiation

```
gclk0_p : IBUFG_LVDS port map
(I=>clk_external, O=>clk_internal);
```

Verilog Instantiation

```
IBUFG_LVDS gclk0_p (.I(clk_external),
.O(clk_internal));
```

Location Constraints

All LVDS buffers must be explicitly placed on a device. For the global clock input buffers this can be done with the following constraint in the UCF or NCF file.

```
NET clk_external LOC = GCLKPAD3;
```

GCLKPAD3 can also be replaced with the package pin name, such as D17 for the BG432 package.

Optional N-Side

Some designers might prefer to also instantiate the N-side buffer for the global clock buffer. This allows the top-level net list to include net connections for both PCB layout and system-level integration. In this case, only the output P-side IBUFG connection has a net connected to it. Since the N-side IBUFG does not have a connection in the EDIF net list, it is trimmed from the design in MAP.

VHDL Instantiation

```
gclk0_p : IBUFG_LVDS port map
(I=>clk_p_external, O=>clk_internal);

gclk0_n : IBUFG_LVDS port map
(I=>clk_n_external, O=>clk_internal);
```

Verilog Instantiation

```
IBUFG_LVDS gclk0_p (.I(clk_p_external),
.O(clk_internal));

IBUFG_LVDS gclk0_n (.I(clk_n_external),
.O(clk_internal));
```

Location Constraints

All LVDS buffers must be explicitly placed on a device. For the global clock input buffers this can be done with the following constraint in the UCF or NCF file.

```
NET clk_p_external LOC = GCLKPAD3;

NET clk_n_external LOC = C17;
```

Virtex-E Switching Characteristics

All devices are 100% functionally tested. Internal timing parameters are derived from measuring internal test patterns. Listed below are representative values. For more specific, more precise, and worst-case guaranteed data, use the values reported by the static timing analyzer (TRCE in the Xilinx Development System) and back-annotated to the simulation net list. All timing parameters assume worst-case operating conditions (supply voltage and junction temperature). Values apply to all Virtex-E devices unless otherwise noted.

IOB Input Switching Characteristics

Input delays associated with the pad are specified for LVTTL levels. For other standards, adjust the delays with the values shown in "IOB Input Switching Characteristics Standard Adjustments" on page 6.

			Speed Grade(2)				
Description(1)	**Symbol**	**Device**	**Min**	**-8**	**-7**	**-6**	**Units**
Propagation Delays							
Pad to I output, no delay	T_{IOPI}	All	0.43	0.8	0.8	0.8	ns, max
Pad to I output, with delay	T_{IOPID}	XCV405E	0.51	1.0	1.0	1.0	ns, max
		XCV812E	0.55	1.1	1.1	1.1	ns, max
Pad to output IQ via transparent latch, no delay	T_{IOPLI}	All	0.75	1.4	1.5	1.6	ns, max
Pad to output IQ via transparent latch, with delay	T_{IOPLID}	XCV405E	1.55	3.5	3.6	3.7	ns, max
		XCV812E	1.55	3.5	3.6	3.7	ns, max
Propagation Delays							
Clock							
Minimum Pulse Width, High	T_{CH}	All	0.56	1.2	1.3	1.4	ns, min
Minimum Pulse Width, Low	T_{CL}		0.56	1.2	1.3	1.4	ns, min
Clock CLK to output IQ	T_{IOCKIQ}		0.18	0.4	0.7	0.7	ns, max
Setup and Hold Times with respect to Clock at IOB Input Register							
Pad, no delay	T_{IOPICK} / T_{IOICKP}	All	0.69 / 0	1.3 / 0	1.4 / 0	1.5 / 0	ns, min
Pad, with delay	$T_{IOPICKD}$ / $T_{IOICKPD}$	XCV405E	1.49 / 0	3.4 / 0	3.5 / 0	3.5 / 0	ns, min
		XCV812E	1.49 / 0	3.4 / 0	3.5 / 0	3.5 / 0	ns, min
ICE input	$T_{IOICECK}$ / $T_{IOCKICE}$	All	0.28 / 0.0	0.55 / 0.01	0.7 / 0.01	0.7 / 0.01	ns, min
SR input (IFF, synchronous)	$T_{IOSRCKI}$	All	0.38	0.8	0.9	1.0	ns, min
Set/Reset Delays							
SR input to IQ (asynchronous)	T_{IOSRIQ}	All	0.54	1.1	1.2	1.4	ns, max
GSR to output IQ	T_{GSRQ}	All	3.88	7.6	8.5	9.7	ns, max

Notes:
1. A Zero "0" Hold Time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed "best-case", but if a "0" is listed, there is no positive hold time.
2. Input timing i for LVTTL is measured at 1.4 V. For other I/O standards, see Table 3.

CLB Switching Characteristics

Delays originating at F/G inputs vary slightly according to the input used, see Figure 2. The values listed below are worst-case. Precise values are provided by the timing analyzer.

Description[1]	Symbol	Speed Grade				Units
		Min	-8	-7	-6	
Combinatorial Delays						
4-input function: F/G inputs to X/Y outputs	T_{ILO}	0.19	0.40	0.42	0.47	ns, max
5-input function: F/G inputs to F5 output	T_{IF5}	0.36	0.76	0.8	0.9	ns, max
5-input function: F/G inputs to X output	T_{IF5X}	0.35	0.74	0.8	0.9	ns, max
6-input function: F/G inputs to Y output via F6 MUX	T_{IF6Y}	0.35	0.74	0.9	1.0	ns, max
6-input function: F5IN input to Y output	T_{F5INY}	0.04	0.11	0.20	0.22	ns, max
Incremental delay routing through transparent latch to XQ/YQ outputs	T_{IFNCTL}	0.27	0.63	0.7	0.8	ns, max
BY input to YB output	T_{BYYB}	0.19	0.38	0.46	0.51	ns, max
Sequential Delays						
FF Clock CLK to XQ/YQ outputs	T_{CKO}	0.34	0.78	0.9	1.0	ns, max
Latch Clock CLK to XQ/YQ outputs	T_{CKLO}	0.40	0.77	0.9	1.0	ns, max
Setup and Hold Times before/after Clock CLK						
4-input function: F/G Inputs	T_{ICK} / T_{CKI}	0.39 / 0	0.9 / 0	1.0 / 0	1.1 / 0	ns, min
5-input function: F/G inputs	T_{IF5CK} / T_{CKIF5}	0.55 / 0	1.3 / 0	1.4 / 0	1.5 / 0	ns, min
6-input function: F5IN input	T_{F5INCK} / T_{CKF5IN}	0.27 / 0	0.6 / 0	0.8 / 0	0.8 / 0	ns, min
6-input function: F/G inputs via F6 MUX	T_{IF6CK} / T_{CKIF6}	0.58 / 0	1.3 / 0	1.5 / 0	1.6 / 0	ns, min
BX/BY inputs	T_{DICK} / T_{CKDI}	0.25 / 0	0.6 / 0	0.7 / 0	0.8 / 0	ns, min
CE input	T_{CECK} / T_{CKCE}	0.28 / 0	0.55 / 0	0.7 / 0	0.7 / 0	ns, min
SR/BY inputs (synchronous)	T_{RCK} / T_{CKR}	0.24 / 0	0.46 / 0	0.52 / 0	0.6 / 0	ns, min
Clock CLK						
Minimum Pulse Width, High	T_{CH}	0.56	1.2	1.3	1.4	ns, min
Minimum Pulse Width, Low	T_{CL}	0.56	1.2	1.3	1.4	ns, min
Set/Reset						
Minimum Pulse Width, SR/BY inputs	T_{RPW}	0.94	1.9	2.1	2.4	ns, min
Delay from SR/BY inputs to XQ/YQ outputs (asynchronous)	T_{RQ}	0.39	0.8	0.9	1.0	ns, max
Toggle Frequency (MHz) (for export control)	F_{TOG}	-	416	400	357	MHz

Notes:

1. A Zero “0” Hold Time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed “best-case”, but if a “0” is listed, there is no positive hold time.

Table 1: **BG560 BGA — XCV405E and XCV812E**

Bank	Pin Description	Pin#
5	IO_L126P_YY	AK23
5	IO_VREF_L126N_YY	AL24
5	IO_L127P_Y	AN26
5	IO_L127N_Y	AJ23
5	IO_L128P_YY	AK24
5	IO_VREF_L128N_YY	AM26[1]
5	IO_L129P_YY	AM27
5	IO_L129N_YY	AJ24
5	IO_L130P_Y	AL26
5	IO_L130N_Y	AK25
5	IO_L131P_YY	AN29
5	IO_VREF_L131N_YY	AJ25
5	IO_L132P_YY	AK26
5	IO_L132N_YY	AM29
5	IO_L133P_Y	AM30
5	IO_L133N_Y	AJ26
5	IO_L134P_YY	AK27
5	IO_VREF_L134N_YY	AL29
5	IO_L135P_YY	AN31
5	IO_L135N_YY	AJ27
5	IO_L136P_Y	AM31
5	IO_L136N_Y	AK28
6	IO	U29
6	IO	AE33
6	IO	AF31
6	IO	AJ32
6	IO	AL33
6	IO_L137N_YY	AH29
6	IO_L137P_YY	AJ30
6	IO_L138N_Y	AK31
6	IO_L138P_Y	AH30
6	IO_L139N_Y	AG29
6	IO_L139P_Y	AJ31
6	IO_VREF_L140N_Y	AK32
6	IO_L140P_Y	AG30
6	IO_L141N_Y	AH31

Table 1: **BG560 BGA — XCV405E and XCV812E**

Bank	Pin Description	Pin#
6	IO_L141P_Y	AF29
6	IO_L142N_Y	AH32
6	IO_L142P_Y	AF30
6	IO_VREF_L143N_YY	AE29
6	IO_L143P_YY	AH33
6	IO_L144N_Y	AG33
6	IO_L144P_Y	AE30
6	IO_L145N_Y	AD29
6	IO_L145P_Y	AF32
6	IO_VREF_L146N_Y	AE31[1]
6	IO_L146P_Y	AD30
6	IO_L147N_Y	AE32
6	IO_L147P_Y	AC29
6	IO_VREF_L148N_YY	AD31
6	IO_L148P_YY	AC30
6	IO_L149N_YY	AB29
6	IO_L149P_YY	AC31
6	IO_L150N_Y	AC33
6	IO_L150P_Y	AB30
6	IO_L151N_Y	AB31
6	IO_L151P_Y	AA29
6	IO_VREF_L152N_Y	AA30[1]
6	IO_L152P_Y	AA31
6	IO_L153N_Y	AA32
6	IO_L153P_Y	Y29
6	IO_L154N_Y	AA33
6	IO_L154P_Y	Y30
6	IO_VREF_L155N_YY	Y32
6	IO_L155P_YY	W29
6	IO_L156N_Y	W30
6	IO_L156P_Y	W31
6	IO_L157N_Y	W33
6	IO_L157P_Y	V30
6	IO_VREF_L158N_Y	V29
6	IO_L158P_Y	V31
6	IO_L159N_Y	V32
6	IO_L159P_Y	U33

Table 1: **BG560 BGA — XCV405E and XCV812E**

Bank	Pin Description	Pin#
7	IO	E30
7	IO	F29
7	IO	F33
7	IO	G30
7	IO	K30
7	IO_L160N_YY	U31
7	IO_L160P_YY	U32
7	IO_L161N_Y	T32
7	IO_L161P_Y	T30
7	IO_L162N_Y	T29
7	IO_VREF_L162P_Y	T31
7	IO_L163N_Y	R33
7	IO_L163P_Y	R31
7	IO_L164N_Y	R30
7	IO_L164P_Y	R29
7	IO_L165N_YY	P32
7	IO_VREF_L165P_YY	P31
7	IO_L166N_Y	P30
7	IO_L166P_Y	P29
7	IO_L167N_Y	M32
7	IO_L167P_Y	N31
7	IO_L168N_Y	N30
7	IO_VREF_L168P_Y	L33[1]
7	IO_L169N_Y	M31
7	IO_L169P_Y	L32
7	IO_L170N_Y	M30
7	IO_L170P_Y	L31
7	IO_L171N_YY	M29
7	IO_L171P_YY	J33
7	IO_L172N_YY	L30
7	IO_VREF_L172P_YY	K31
7	IO_L173N_Y	L29
7	IO_L173P_Y	H33
7	IO_L174N_Y	J31
7	IO_VREF_L174P_Y	H32[1]
7	IO_L175N_Y	K29

Table 1: **BG560 BGA — XCV405E and XCV812E**

Bank	Pin Description	Pin#
7	IO_L175P_Y	H31
7	IO_L176N_Y	J30
7	IO_L176P_Y	G32
7	IO_L177N_YY	J29
7	IO_VREF_L177P_YY	G31
7	IO_L178N_Y	E33
7	IO_L178P_Y	E32
7	IO_L179N_Y	H29
7	IO_L179P_Y	F31
7	IO_L180N_Y	D32
7	IO_VREF_L180P_Y	E31
7	IO_L181N_Y	G29
7	IO_L181P_Y	C33
7	IO_L182N_Y	F30
7	IO_L182P_Y	D31
2	CCLK	C4
3	DONE	AJ5
NA	DXN	AK29
NA	DXP	AJ28
NA	M0	AJ29
NA	M1	AK30
NA	M2	AN32
NA	PROGRAM	AM1
NA	TCK	E29
NA	TDI	D5
2	TDO	E6
NA	TMS	B33
NA	NC	C31
NA	NC	AC2
NA	NC	AK4
NA	NC	AL3
NA	VCCINT	A21
NA	VCCINT	B12
NA	VCCINT	B14

Table 1: **BG560 BGA — XCV405E and XCV812E**

Bank	Pin Description	Pin#
NA	GND	A1
NA	GND	A7
NA	GND	A12
NA	GND	A14
NA	GND	A18
NA	GND	A20
NA	GND	A24
NA	GND	A29
NA	GND	A32
NA	GND	A33
NA	GND	B1
NA	GND	B6
NA	GND	B9
NA	GND	B15
NA	GND	B23
NA	GND	B27
NA	GND	B31
NA	GND	C2
NA	GND	E1
NA	GND	F32
NA	GND	G2
NA	GND	G33
NA	GND	J32
NA	GND	K1
NA	GND	L2
NA	GND	M33
NA	GND	P1
NA	GND	P33
NA	GND	R32
NA	GND	T1
NA	GND	V33
NA	GND	W2
NA	GND	Y1
NA	GND	Y33
NA	GND	AB1
NA	GND	AC32

Table 1: **BG560 BGA — XCV405E and XCV812E**

Bank	Pin Description	Pin#
NA	GND	AD33
NA	GND	AE2
NA	GND	AG1
NA	GND	AG32
NA	GND	AH2
NA	GND	AJ33
NA	GND	AL32
NA	GND	AM3
NA	GND	AM7
NA	GND	AM11
NA	GND	AM19
NA	GND	AM25
NA	GND	AM28
NA	GND	AM33
NA	GND	AN1
NA	GND	AN2
NA	GND	AN5
NA	GND	AN10
NA	GND	AN14
NA	GND	AN16
NA	GND	AN20
NA	GND	AN22
NA	GND	AN27
NA	GND	AN33

Notes:
1. V_{REF} or I/O option only in the XCV812E.

Table 3: **FG676 Fine-Pitch BGA — XCV405E**

Bank	Pin Description	Pin #
5	IO_L118N_YY	AD12
5	IO_L119P_YY	AC12
5	IO_VREF_L119N_YY	AB12
5	IO_L120P_YY	AD11
5	IO_L120N_YY	Y12
5	IO_L121P	AB11
5	IO_L121N	AD10
5	IO_L122P_YY	AC11
5	IO_L122N_YY	AE10
5	IO_L123P_YY	AC10
5	IO_L123N_YY	AA11
5	IO_L124P_Y	Y11
5	IO_L124N_Y	AD9
5	IO_L125P_YY	AB10
5	IO_L125N_YY	AF9
5	IO_L126P_YY	AD8
5	IO_VREF_L126N_YY	AA10
5	IO_L127P_YY	AE8
5	IO_L127N_YY	Y10
5	IO_L128P_Y	AC9
5	IO_L128N_Y	AF8
5	IO_L129P_Y	AF7
5	IO_L129N_Y	AB9
5	IO_L130P_YY	AA9
5	IO_L130N_YY	AF6
5	IO_L131P_YY	AC8
5	IO_VREF_L131N_YY	AC7
5	IO_L132P_YY	AD6
5	IO_L132N_YY	Y9
5	IO_L133P_YY	AE5
5	IO_L133N_YY	AA8
5	IO_L134P_YY	AC6
5	IO_VREF_L134N_YY	AB8
5	IO_L135P_YY	AD5
5	IO_L135N_YY	AA7

Table 3: **FG676 Fine-Pitch BGA — XCV405E**

Bank	Pin Description	Pin #
5	IO_L136P_Y	AF4
5	IO_L136N_Y	AC5
6	IO	P3
6	IO	AA3
6	IO	W3
6	IO	Y2
6	IO	Y6
6	IO_L137N_YY	AA5
6	IO_L137P_YY	AC3
6	IO_L138N_YY	AC2
6	IO_L138P_YY	AB4
6	IO_L139N_Y	W6
6	IO_L139P_Y	AA4
6	IO_VREF_L140N_Y	AB3
6	IO_L140P_Y	Y5
6	IO_L141N_Y	AB2
6	IO_L141P_Y	V7
6	IO_L142N_YY	AB1
6	IO_L142P_YY	Y4
6	IO_VREF_L143N_YY	V5
6	IO_L143P_YY	W5
6	IO_L144N_YY	AA1
6	IO_L144P_YY	V6
6	IO_L145N_Y	W4
6	IO_L145P_Y	Y3
6	IO_L146N_Y	Y1
6	IO_L146P_Y	U7
6	IO_L147N_YY	W1
6	IO_L147P_YY	V4
6	IO_L148N_YY	W2
6	IO_VREF_L148P_YY	U6
6	IO_L149N_YY	V3
6	IO_L149P_YY	T5
6	IO_L150N_YY	U5

Table 3: **FG676 Fine-Pitch BGA — XCV405E**

Bank	Pin Description	Pin #
1	VCCO	H15
2	VCCO	N18
2	VCCO	M19
2	VCCO	M18
2	VCCO	L19
2	VCCO	K19
2	VCCO	J19
3	VCCO	V19
3	VCCO	U19
3	VCCO	T19
3	VCCO	R19
3	VCCO	R18
3	VCCO	P18
4	VCCO	W18
4	VCCO	W17
4	VCCO	W16
4	VCCO	W15
4	VCCO	V15
4	VCCO	V14
5	VCCO	W9
5	VCCO	W12
5	VCCO	W11
5	VCCO	W10
5	VCCO	V13
5	VCCO	V12
6	VCCO	V8
6	VCCO	U8
6	VCCO	T8
6	VCCO	R9
6	VCCO	R8
6	VCCO	P9
7	VCCO	N9
7	VCCO	M9
7	VCCO	M8
7	VCCO	L8

Table 3: **FG676 Fine-Pitch BGA — XCV405E**

Bank	Pin Description	Pin #
7	VCCO	K8
7	VCCO	J8
NA	GND	V25
NA	GND	V2
NA	GND	U17
NA	GND	U16
NA	GND	U15
NA	GND	U14
NA	GND	U13
NA	GND	U12
NA	GND	U11
NA	GND	U10
NA	GND	T17
NA	GND	T16
NA	GND	T15
NA	GND	T14
NA	GND	T13
NA	GND	T12
NA	GND	T11
NA	GND	T10
NA	GND	R17
NA	GND	R16
NA	GND	R15
NA	GND	R14
NA	GND	R13
NA	GND	R12
NA	GND	R11
NA	GND	R10
NA	GND	P25
NA	GND	P17
NA	GND	P16
NA	GND	P15
NA	GND	P14
NA	GND	P13

Table 5: **FG900 Fine-Pitch BGA Package — XCV812E**

Bank	Description	Pin
0	IO_L29N	D14
0	IO_L29P	B14
0	IO_L30N_YY	A14
0	IO_L30P_YY	J14
0	IO_VREF_L31N_YY	K14
0	IO_L31P_YY	J15
0	IO_LVDS_DLL_L34N	A15
1	GCk2	E15
1	IO	B18
1	IO	B21
1	IO	B28
1	IO	C23
1	IO	C26
1	IO	D20
1	IO	D23
1	IO_LVDS_DLL_L34P	E16
1	IO_L35N	B16
1	IO_L35P	F16
1	IO_L36N	A16
1	IO_L36P	H16
1	IO_L37N_YY	C16
1	IO_VREF_L37P_YY	K15
1	IO_L38N_YY	K16
1	IO_L38P_YY	G16
1	IO_L39N	A17
1	IO_L39P	E17
1	IO_L40N	F17
1	IO_L40P	C17
1	IO_L41N_YY	E18
1	IO_VREF_L41P_YY	A18
1	IO_L42N_YY	D18
1	IO_L42P_YY	A19
1	IO_L43N	B19

Table 5: **FG900 Fine-Pitch BGA Package — XCV812E**

Bank	Description	Pin
1	IO_L43P	G18
1	IO_L44N	D19
1	IO_L44P	H18
1	IO_L45N_YY	F18
1	IO_VREF_L45P_YY	F19
1	IO_L46N_YY	B20
1	IO_L46P_YY	K17
1	IO_L48N_Y	G19
1	IO_L48P_Y	C20
1	IO_L49N_Y	K18
1	IO_L49P_Y	E20
1	IO_L51N_YY	F20
1	IO_L51P_YY	A21
1	IO_L52N_YY	C21
1	IO_VREF_L52P_YY	A22
1	IO_L53N	H19
1	IO_L53P	B22
1	IO_L54N	E21
1	IO_L54P	D22
1	IO_L55N_YY	F21
1	IO_VREF_L55P_YY	C22
1	IO_L56N_YY	H20
1	IO_L56P_YY	E22
1	IO_L57N	G21
1	IO_L57P	A23
1	IO_L58N	A24
1	IO_L58P	K19
1	IO_L59N_YY	C24
1	IO_VREF_L59P_YY	B24
1	IO_L60N_YY	H21
1	IO_L60P_YY	G22
1	IO_L61N	E23
1	IO_L61P	C25
1	IO_L62N	D24

Table 5: **FG900 Fine-Pitch BGA Package — XCV812E**

Bank	Description	Pin
5	IO_VREF_5_L198N_YY	AF9
5	IO_L199P_YY	AH9
5	IO_L199N_YY	AK9
5	IO_L200P	AF8
5	IO_L200N	AB11
5	IO_L201P	AC11
5	IO_L201N	AG8
5	IO_L202P_YY	AK8
5	IO_VREF_5_L202N_YY	AF7
5	IO_L203P_YY	AG7
5	IO_L203N_YY	AK7
5	IO_L204P	AJ7
5	IO_L204N	AD10
5	IO_L205P	AH6
5	IO_L205N	AC10
5	IO_L206P_YY	AD9
5	IO_VREF_5_L206N_YY	AG6
5	IO_L207P_YY	AB10
5	IO_L207N_YY	AJ5
5	IO_L209P_Y	AC9
5	IO_L209N_Y	AJ4
5	IO_L210P_Y	AG5
5	IO_L210N_Y	AK4
6	IO	T6
6	IO	U1
6	IO	U6
6	IO	V7
6	IO	V8
6	IO	W10
6	IO	Y10
6	IO	AA2
6	IO	AA4
6	IO	AD1

Table 5: **FG900 Fine-Pitch BGA Package — XCV812E**

Bank	Description	Pin
6	IO	AD6
6	IO	AG2
6	IO_L212N_YY	AF3
6	IO_L212P_YY	AC6
6	IO_L214N_Y	AB9
6	IO_L214P_Y	AE4
6	IO_L215N	AE3
6	IO_L215P	AH1
6	IO_L217N	AG1
6	IO_L217P	AA10
6	IO_VREF_L218N_Y	AA9
6	IO_L218P_Y	AD4
6	IO_L219N_YY	AD5
6	IO_L219P_YY	AD2
6	IO_L220N	AD3
6	IO_L220P	AF2
6	IO_L221N	AA8
6	IO_L221P	AA7
6	IO_VREF_L222N_YY	AF1
6	IO_L222P_YY	Y9
6	IO_L223N_YY	AB6
6	IO_L223P_YY	AC4
6	IO_L224N_Y	AE1
6	IO_L224P_Y	W8
6	IO_L225N	Y8
6	IO_L225P	AB4
6	IO_VREF_L226N	AB3
6	IO_L226P	W9
6	IO_L228N	AB1
6	IO_L228P	V10
6	IO_VREF	AC1
6	IO_L230N	V11
6	IO_L230P	AA3
6	IO_L232N_Y	W7

Table 5: **FG900 Fine-Pitch BGA Package — XCV812E**

Bank	Description	Pin
NA	GND	AC8
NA	GND	H8
NA	GND	AD7
NA	GND	B8
NA	GND	AE6
NA	GND	G7
NA	GND	F6
NA	GND	AF5
NA	GND	E5
NA	GND	AG4
NA	GND	D4
NA	GND	V3
NA	GND	N3
NA	GND	C3
NA	GND	AK2
NA	GND	AH3
NA	GND	AC2
NA	GND	H2
NA	GND	B2
NA	GND	A2
NA	GND	AK1
NA	GND	AJ2
NA	GND	AJ1
NA	GND	A1
NA	GND	B1

FG900 Differential Pin Pairs

Virtex-E Extended Memory devices have differential pin pairs that can also provide other functions when not used as a differential pair. A √ in the AO column indicates that the pin pair can be used as an asynchronous output for all devices provided in this package.

Pairs with a note number in the AO column are device dependent. They can have asynchronous outputs if the pin pair is in the same CLB row and column in the device. Numbers in this column refer to footnotes that indicate which devices have pin pairs that can be asynchronous outputs. The Other Functions column indicates alternative function(s) not available when the pair is used as a differential pair or differential clock.

Table 6: **FG900 Differential Pin Pair Summary — XCV812E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
GCLK LVDS					
3	0	C15	A15	NA	IO LVDS 34
2	1	E15	E16	NA	IO LVDS 34
1	5	AK16	AH16	NA	IO LVDS 177
0	4	AJ16	AF16	NA	IO LVDS 177
IO LVDS Total Pairs: 235, Asynchronous Output Pairs: 85					
1	0	G8	D5	√	-
2	0	H9	A3	√	-
4	0	D6	A4	√	-
5	0	B5	E7	√	VREF
6	0	F8	A5	-	-
7	0	N11	D7	-	-
8	0	E8	G9	√	-
9	0	J11	A6	√	VREF
10	0	B7	C7	-	-
11	0	H10	C8	-	-
12	0	F10	G10	√	-
13	0	H11	A8	√	VREF
15	0	J12	B9	-	-
17	0	B10	G11	-	-
19	0	F11	H13	√	-
20	0	D11	E11	√	-
22	0	C11	F12	√	-
23	0	D12	A10	√	VREF
24	0	A11	E12	-	-

Table 6: **FG900 Differential Pin Pair Summary — XCV812E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
201	5	AC11	AG8	-	-
202	5	AK8	AF7	√	VREF
203	5	AG7	AK7	√	-
204	5	AJ7	AD10	-	-
205	5	AH6	AC10	-	-
206	5	AD9	AG6	√	VREF
207	5	AB10	AJ5	√	-
209	5	AC9	AJ4	√	-
210	5	AG5	AK4	√	-
212	6	AC6	AF3	√	-
214	6	AE4	AB9	√	-
215	6	AH1	AE3	-	-
217	6	AA10	AG1	-	-
218	6	AD4	AA9	√	VREF
219	6	AD2	AD5	√	-
220	6	AF2	AD3	-	-
221	6	AA7	AA8	-	-
222	6	Y9	AF1	√	VREF
223	6	AC4	AB6	√	-
224	6	W8	AE1	√	-
225	6	AB4	Y8	-	-
226	6	W9	AB3	-	VREF
228	6	V10	AB1	-	-
230	6	AA3	V11	-	-
232	6	AA6	W7	√	-
233	6	Y4	Y6	-	-
235	6	Y2	Y3	-	-
236	6	W5	Y5	√	VREF
237	6	W6	W4	√	-
238	6	W2	V6	-	-
239	6	V4	U9	-	-
240	6	T8	AB2	√	VREF
241	6	W1	U5	√	-
242	6	T9	Y1	√	-
243	6	U3	T7	-	-
244	6	V2	T5	-	VREF
246	6	U2	T4	-	-

Table 6: **FG900 Differential Pin Pair Summary — XCV812E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
247	7	R10	T1	-	IRDY
249	7	R4	R8	-	-
250	7	R3	R7	-	-
251	7	P6	P10	-	VREF
252	7	P2	P5	-	-
253	7	P4	P7	√	-
254	7	R2	N4	√	-
255	7	P1	N7	√	VREF
256	7	N6	M6	-	-
257	7	N1	N5	-	-
258	7	M5	M4	√	-
259	7	M1	M2	√	VREF
260	7	L2	L4	-	-
262	7	M8	L1	-	-
263	7	M9	K2	√	-
265	7	K1	K5	√	-
266	7	K3	L6	√	VREF
267	7	K4	L7	-	-
268	7	J5	L8	-	-
269	7	H4	K6	-	VREF
270	7	K7	H1	-	-
271	7	J2	J7	√	-
272	7	G2	H5	√	-
273	7	G5	L9	√	VREF
274	7	K8	F3	-	-
275	7	E1	G3	-	-
276	7	E2	H6	√	-
277	7	K9	E4	√	VREF
278	7	F4	J8	-	-
280	7	C2	G6	-	-
281	7	F5	D2	-	-

Virtex-E Extended Memory Device/Package Combinations and Maximum I/O

Virtex-E Extended Memory Series Maximum User I/O by Device/Package (Excluding Dedicated Clock Pins)		
Package	**XCV405E**	**XCV812E**
BG560	404	404
FG676	404	
FG900		556

Virtex-E Ordering Information

Virtex-II ordering information is shown in Figure 1

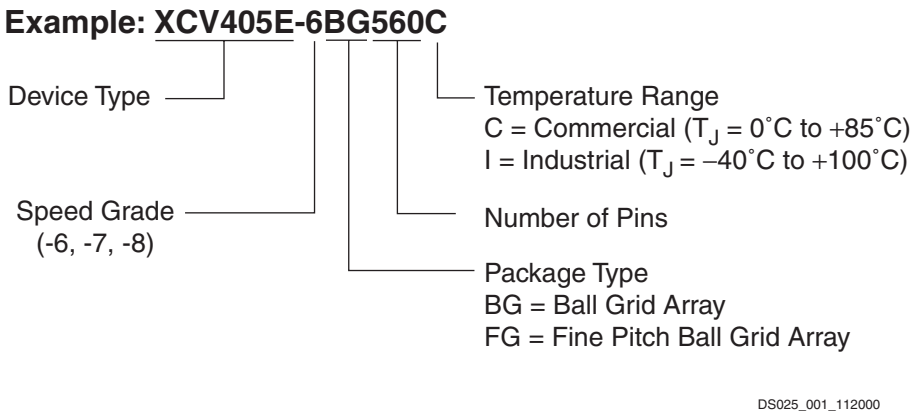

Figure 1: **Virtex Ordering Information**